

Method and Device for Determining the Pressure Distribution for Bonding

Abstract

This invention relates to a method and a device for determining the pressure distribution for bonding of a first substrate to a second substrate, with the following steps, especially with the following sequence:

- placing a measurement layer (7, 7', 7'') between a first tool (1) for holding the first substrate and an opposite second tool (5) which is aligned to the first tool (1) for bonding of the substrate,
- deformation of the measurement layer (7, 7', 7'') by bringing the tools (1, 5) closer to one another,
- measurement of the deformation of the measurement layer (7, 7', 7'') and
- computation of the pressure distribution.

Figure 1f